

This Sheet Has Been Replaced



[Document type] Abstract

[Abstract]

[Object]

To reduce the manufacturing costs of semiconductor packaging while maintaining the heat dissipation of the semiconductor packaging in a good state.

[Constitution]

A heat sink 22 is hydroxylated by degreasing with alkali, cleaning with water and drying. Thereafter, a diluted silane coupling agent is applied to the surface of the heat sink 22, and the heat sink 22 is dried to form a layer A of the silane coupling agent on the surface of the heat sink 22. Then, a chip 12 carried by the die pad 16 and lead frames 18 connected to the chip 12 with wires 20 are placed in the die, the heat sink 22 is placed in the same die, and the system is molded to form a semiconductor packaging 10.

[Selected Drawing] Figure 1